CRYSTAL CLEAR TECHNOLOGY

Product Specification

T400A01X00X

(REVISION 1)

Customers are requested to read through and understand this product specification. If no feedback is received from customer by 30 days, it is deemed that customer has fully need, understand and agreed on the specification set forth in this document.

Acknowledged by,

Date:

(CUSTOMER'S SIGNATURE)

REMARK: AFTER THE ACKNOWLEDGEMENT HAS BEEN SIGNED, PLEASE RETURN TO CCT.

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1. Table of Contents

No	Title	Page
1	Table of Contents	2
2	Record of Revision	3
3	General Specification	4
4	AC/DC Characteristics (TFT)	5
5	AC/DC Characteristics (CTP)	12
6	Optical Characteristics	14
7	Reliability Test Condition	17
8	Inspection Criteria	18
9	Precaution	21
10	Mechanical Specification	25



2. Record of Revision

Rev	Date	Item	Page	Comment	Prepared	Checked
1.0	22.11.19			Initial Release	SCChong	W.Hong

3. General Specification

T400A01X00X is 4.0" color TFT-LCD (Thin Film Transistor Liquid Crystal Display) module composed of LCD panel, driver ICs control circuit, LED backlight with or without CTP (Capacitive Touch Panel). This display area contains 480(RGB) x800 pixels and can display up to 16.7M colors. This product compliant with RoHS environmental requirement.

	Item	Specifications	Unit	Note
	Size (Diagonal)	4.0"	inch	
	Outline dimensions	57.14(W) x 96.85(H) x 2.10(T)	mm	(1)
	Display type	16.7M color TFT IPS, Normally Black	-	(2)
	Viewing direction	All	O'clock	
	TFT Active area	51.84(W) x 86.40(H)	mm	
	TFT Resolution	480(RGB) x 800	-	
TFT	Pixel size	0.1080(W) x 0.1080(H)	mm	
•	Pixel arrangement	Pixel arrangement RGB vertical strip		
	TFT Driving IC ST7701SI or Equivalent		-	
	TFT Interface mode MIPI		-	
	Luminance	Luminance 320 (TYP)		(3)
	CTP Active area	51.84(W) x 86.40(H)	mm	
	CTP Resolution	480 x 800	-	
	CTP Origin	Top-left (FPC down)	-	
<u>م</u>	CTP Controller	FT5436	-	
СТР	CTP Interface mode	I2C	-	
	Touch mode	5 fingers multi touch	-	
	Cover lens material	ver lens material Glass		
	Transparency	85	%	
	Operating temperature	-10 ~ +60	°C	(4)
	Storage temperature	-20 ~ +70	°C	(4)

Note:

(1) FPC or Wire or Foam Tape or CTP are not included.

(2) Color tone is slightly changed by temperature and driving voltage.

- (3) Brightness on LCD surface. Module with CTP or RTP, brightness will be about 20% (max) lower on the touch panel surface.
- (4) This product specification shows range of value either in the minimum, typical or maximum category. Operating under extreme condition, bordering on the minimum or maximum range, does not mean that the product can survive perpetually under these extremities. In fact, it only means that the product can operate under such condition with no information of lifetime, other than those already indicated in the specification. User is advised to test it on their own if the specification's reliability data did not indicate it.

4. AC/DC Characteristics (TFT)

Item	Symbol	Min	Тур	Max	Unit	Note
Power Supply Voltage	Vdd	-0.3	-	+4.6	V	
Input Voltage (I/O)	Vddio	-0.3	-	+4.6	V	
Backlight Forward Current	lf	-	-	30	mA	
Storage Humidity	HST	10	-	90	%RH	(1)
Storage Temperature	Tst	-20	-	+70	°C	
Operating Humidity	Нор	10	-	90	%RH	(1)
Operating Temperature	Тор	-10	-	+60	°C	

4.1 Absolute Maximum Ratings (Vss = 0V, Ta = 25°C)

Note:

- (1) At 25±5°C. Absolute humidity shall be less than 90%RH at +50°C.
- (2) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

4.2 Electrical Characteristics (VS	ss = 0V, VDD = 3.3V, Ta = 25°C)
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Item	Symbol	Min	Тур	Max	Unit	Note
Power Supply Voltage	Vdd	2.5	-	3.6	V	
Interface Operation Voltage	Vddio	1.65	-	3.6	V	
Operation Current	IDD		TBD			
Low Level Input Voltage	VIL	0	-	0.3Vddio	V	
High Level Input Voltage	VIH	0.7Vddio	-	Vddio	V	
Low Level Output Voltage	Vol	0	-	0.2Vddio	V	
High Level Output Voltage	Voн	0.8Vddio	-	Vddio	V	
Differential Input High Threshold Voltage	VIT+	-	0	50	mV	
Differential Input Low Threshold Voltage	VIT-	-50	0	-	mV	MIPI_CLK
Single-ended Receiver Input Operation Voltage Range	VIR	0.5	-	1.2	V	MIPI_Data

Note:

(1) The recommended operating conditions refer to a range in which operation of this product is guaranteed. Accordingly, please make sure that the module is used within this range. And these current values are measured under the condition that all devices are stopped, each component is stable and logic signal is input.



4.3 LED Backlight Specification (Ta = 25°C)

Item	Symbol	Condition	Min	Тур	Мах	Unit	
LED Supply Voltage	Vf	lf = 20mA	-	24.0	26.4	V	
LED Supply Current	lf		-	20	-	mA	
Luminous Intensity	Lv	White	-	320	-	cd/m ²	
Half Life Expectancy	LL	lf = 20mA/LED	20000	-	-	hrs	
LED Configuration	8 White LED, 8 in Series						

Note:

- (1) The LED Supply Voltage is defined by the number of LED at Ta = 25°C and If = 20mA.
- (2) The "Half Life Expectancy" is defined as the module brightness decrease to 50% of original brightness at Ta = 25°C and If = 20mA/LED. The LED lifetime can decrease if the operating If is higher than 20mA/LED.
- (3) Brightness measurement done at LCD surface.

4.4 MIPI Interface Characteristics (Vss = 0V, VDD = 3.3V, Ta = 25°C)

4.4.1 High Speed Mode

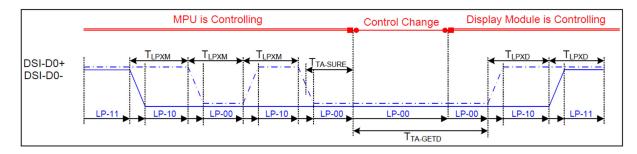


DSI Clock Channel Timing

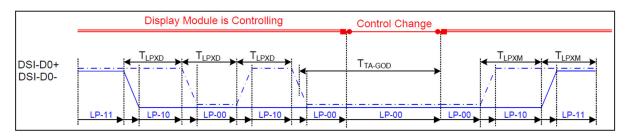
Signal	Symbol	Parameter	MIN	MAX	Unit	Description
DSI-CLK+/-	2xUI _{INSTA}	Double UI instantaneous	4	25	ns	
DSI-CLK+/-	UI _{INSTA} UI _{INSTB}	UI instantaneous halfs	2	12.5	ns	UI = UI _{INSTA} = UI _{INSTB}
DSI-Dn+/-	tDS	Data to clock setup time	0.15	-	UI	
DSI-Dn+/-	tDH	Data to clock hold time	0.15	-	UI	

MIPI Interface - High Speed Mode Timing Characteristics

4.4.2 Lower Power Mode



Bus Turnaround (BTA) from display module to MPU timing



Bus Turnaround (BTA) from MPU to display module timing

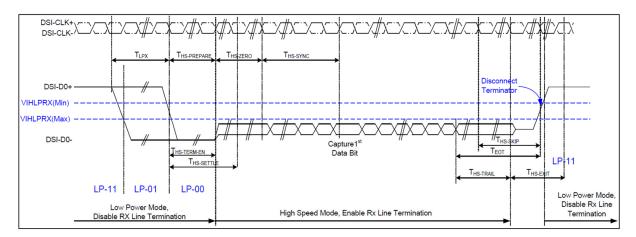


Spec No. T400A01X00X REV1

Signal	Symbol	Parameter	MIN	MAX	Unit	Description	
		Length of LP-00,LP-01,					
DSI-D0+/-	TLPXM	LP-10 or LP-11 periods	50	75	ns	Input	
		MPU → Display Module					
		Length of LP-00,LP-01,					
DSI-D0+/-	TLPXD	LP-10 or LP-11 periods	50	75	ns	Output	
		MPU → Display Module					
DSI-D0+/-	TTA-SURED	Time-out before the MPU	TLPXD	2xT _{LP}	20	Output	
D3I-D0+/-	TIA-SURED	start driving	LPXD	XD	ns	Output	
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by	5vT		ns	loout	
D3I-D0+/-	TIA-GETD	display module	J	5xT _{lpxd}		Input	
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after	4vT		20	Output	
D3I-D0+/-	TIA-GOD	turnaround request-MPU	4X1	LPXD	ns	Output	

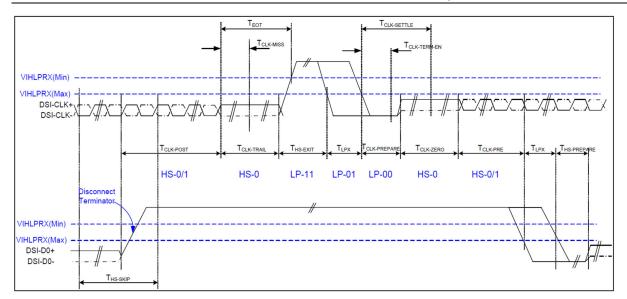
MIPI Interface - Low Power Mode Timing Characteristics

4.4.3 DSI Bursts Mode



Data lanes – Lower Power Mode to/from High Speed Mode Timing





Clock lanes - High Speed Mode to/from Lower Power Mode Timing

Signal	Symbol	Parameter	MIN	MAX	Unit	Description			
Low Power Mode to High Speed Mode Timing									
DSI-Dn+/-	TLPX	Length of any low power state period	50	-	ns	Input			
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare	40+4	85+6	ns	Input			
001-011+/-	THO-FREFARE	for HS transmission	UI	UI	115	input			
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from		35+4	20	loput			
D3I-DII+/-	THS-TERIVI-EN	when Dn crosses VILMAX	-	UI	ns	Input			
DSI-Dn+/-	THS-PREPARE	THS-PREPARE + time to drive	140+		20	Input			
DSI-DN+/-	+ THS-ZERO	HS-0 before the sync sequence	10UI	-	ns	Input			
	ł	High Speed Mode to Low Power Me	ode Timi	ng					
		Time-out at display module to	10	55+4		land			
DSI-Dn+/-	THS-SKIP	ignore transition period of EoT	40	UI	ns	Input			
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input			
DSI-Dn+/-	THS-TRAIL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4		ns	Input			
			UI		115	Input			



	Hig	h Speed Mode to/from Low Power	Mode Ti	ming		
DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode	60+5 2UI	-	ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for HS transmission	38	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time-out at clock lan display module to enable HS transmission		38	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Minimum lead HS-0 drive	300		ns	Input
DOI-CLK+/-	+ TCLK-ZERO	period before starting clock	300	-	115	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8UI	-	ns	Input
				105n		
DSI-CLK+/-	TEOT	Time form start of TCLK-TRAIL period to start of LP-11 state	-	s+12	ns	Input
				UI		

4.5 Pin Assignment Table

Pin No.	Symbol	I/O	Description	Note
1	LCD_ID	-	DUMMY	
2	GND	Р	Ground	
3	LEDPWM	0	The PWM frequency output for LCD driver control	
4	GND	Р	Ground	
5	Reset	I	Chip reset pin	(1)
6	VDDIO	Р	Power Supply	
7	GND	Р	Ground	
8	D0N	Ι	MIPI DSI differential data pair (DSI-D0-)	
9	NC	-	DUMMY	
10	D0P	Ι	MIPI DSI differential data pair (DSI-D0+)	
11	GND	Р	Ground	
12	CN	I	MIPI DSI differential clock pair (DSI-CLK-)	
13	NC	-	DUMMY	
14	СР	I	MIPI DSI differential clock pair (DSI-CLK+)	
15	GND	Р	Ground	
16	D1N	Ι	MIPI DSI differential data pair (DSI-D1-)	
17	NC	-	DUMMY	
18	D1P	Ι	MIPI DSI differential data pair (DSI-D1+)	
19	GND	Р	Ground	
20	NC	-	DUMMY	
21	VDD	Р	Power Supply	
22	TE	0	F mark signal	
23	VLED-	Р	LED Backlight (Cathode)	
24	VLED+	Р	LED Backlight (Anode)	
25	GND	Ρ	Ground	

Note: (1) RESET : Active low

5. AC/DC Characteristics (CTP)

Item	Symbol	Min	Тур	Max	Unit	Note
Power Supply Voltage	Vcc	2.7	-	3.6	V	
Storage Humidity	Hst	10	-	90	%RH	(1)
Storage Temperature	Tst	-20	-	+70	°C	
Operating Humidity	Нор	10	-	90	%RH	(1)
Operating Temperature	Тор	-10	-	+60	°C	

5.1 Absolute Maximum Ratings (VSS = 0V, Ta = 25°C)

Note:

- (1) At 25±5°C. Absolute humidity shall be less than 90%RH at +50°C.
- (2) Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Item	Symbol	Min	Тур	Max	Unit	Note
Power Supply Voltage	Vcc	2.8	-	3.3	V	
Operation Current	lcc	-	10	13	mA	
Low Level Input Voltage	VIL	-0.3	-	0.3 Vcc	V	
High Level Input Voltage	VIH	-	-	Vcc	V	
Low Level Output Voltage	Vol	-	-	0.3Vcc	V	
High Level Output Voltage	Vон	0.7Vcc	-	-	V	
I/O leakage current	ILI	-1	-	1	uA	

5.2 Electrical Characteristics (VSS = 0V, VCC = 3.3V, Ta = 25°C)

Note:

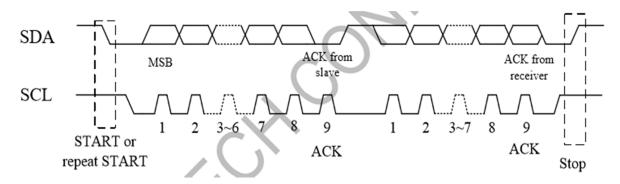
(1) The recommended operating conditions refer to a range in which operation of this product is guaranteed. Accordingly, please make sure that the module is used within this range. And these current values are measured under the condition that all devices are stopped, each component is stable and logic signal is input.

5.3 I2C Interface

Touch panel is used as I2C slave device, I2C slave address is 0x70, refer FT5436 datasheet for details.

There are three communication pins connected between host and CTP module which are including external interrupt INT, I2C pins SCL and SDA. The INT is active low while the touch state is calculated by CTP module and the touch information can be translated via I2C communication interface.

5.4 I2C Timing Characteristics (VSS = 0V, VCC = 3.3V,Ta = 25°C)



Parameter	Min	Max	Unit
SCL frequency	0	400	KHz
Bus free time between a STOP and START condition	1.3		us
Hold time (repeated) START condition	0.6		us
Data setup time	100		ns
Setup time for a repeated START condition	0.6		us
Setup Time for STOP condition	0.6		us

5.5 Pin Assignment Table

1	GND	Р	Ground	
2	SCL	I	I2C Serial Clock	
3	SDA	I/O	I2C Serial Data	
4	VCC	Р	Power Supply	
5	INT	0	Interrupt	(1)
6	RST	I	Reset	(2)

Note:

(1) INT (CTP): Active low

(2) RST (CTP) : Active low

6. Optical Characteristics

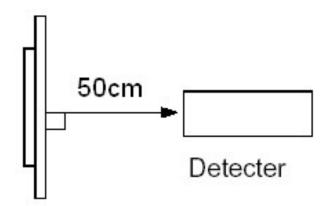
Item	Symbol	Condition	Min	Тур	Max	Unit	Note
Brightness	Вр	<i>θ</i> =0°	-	320	-	cd/m ²	(2)
Uniformity	⊿Bp	Ф=0°	70	80	-	%	(2)(3)
	3:00	-	80	-			
	6:00	Cr≥10	-	80	-	degree	(4)
Viewing Angle	9:00		-	80	-		
	12:00		-	80	-		
Contrast Ratio	Cr	<i>θ</i> =0°	720	900	-	-	(5)
Response Time	Tr + Tf	Φ=0°	-	35	45	ms	(6)
NTSC Ratio	S	T=25°C	-	70	-	%	(7)
CTP Transmittance	Т		85	90	-	%	(8)

Note:

- (1) The parameter is slightly changed by temperature, driving voltage and material.
- (2) The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment BM-7A. Measuring condition:
 - Measuring surroundings: Dark room.
 - Measuring temperature: Ta=25°C.
 - Adjust operating voltage to get optimum contrast at the center of the display.

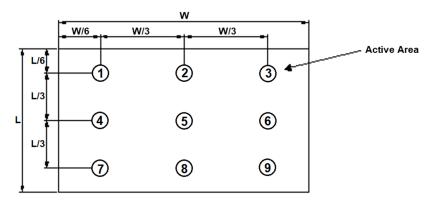
Measured value at the center point of LCD panel after more than 5 minutes while backlight turning on.

- Measurement I son TFT surface

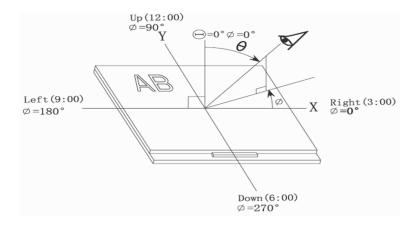




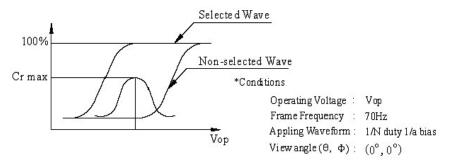
(3) The luminance uniformity is calculated by using following formula:
 ⊿Bp = Bp (Min.) / Bp (Max.) × 100 (%)
 Bp (Max.) = Maximum brightness in 9 measured spots.
 Bp (Min.) = Minimum brightness in 9 measured spots.

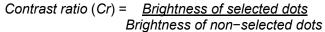


(4) The definition of viewing angle: Refer to the graph below marked by θ and Φ



(5) Definition of contrast ratio.

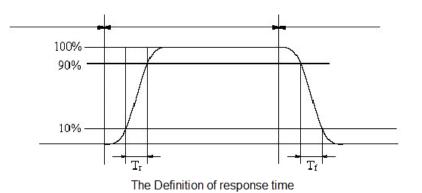




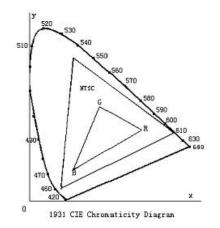


(6) Definition of Response time.

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.



(7) Definition of Color of CIE Coordinate and NTSC Ratio.



(8) Definition of the transmittance measurements shall be made at viewing angle of $\theta = 0^{\circ}$ and at the center of the touch panel by using BM-7A. Transmittance shall be calculated by the difference of the luminance between a standard light source with touch panel and a standard light source without touch panel.

Transmittance = <u>Luminance on touch panel surface</u> Luminance of standard light source

7. Reliability Test Condition

ltem		Test Condition	Note
	High Temperature	+60°C, 240hrs	(3)
	Low Temperature	-10°C, 240hrs	(3)
Operating	High Temperature and High Humidity	+50°C, 90%RH, 240hrs	(3)(4)
	Cycle	RT (0m) → -10°C (30m) → RT (5m) → +60°C (30m) → RT (5m)	(1)(2)(3)
		50 cycles	
Storage	High Temperature	+70°C, 240hrs	(3)
Storage	Low Temperature	-20°C, 240hrs	(3)

Note:

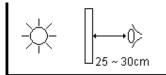
- (1) RT means Room Temperature.
- (2) m means minute.
- (3) Before cosmetic and functional test, the product must have enough recovery time, at least 2 hours at room temperature.

(4) No condensation



8. Inspection Criteria

- Inspection distance: 25~30cm.
- From lamp source to product: 250 ± 100cm.
- Angle of inspection: Ambient brightness 1k-1.5k lux inspection from front view, perpendicular to the surface of product.



No	Defect	Definition of defect	Inspection Criteria
	a) Definition of dot	The size of defective dot over $\frac{1}{2}$ of whole is regards as one defective dot. Smaller than $\frac{1}{2}$ Larger than $\frac{1}{2}$ R G B 'No dot defect' (ignero)	A – Viewing Area B – Outside viewing area
1	b) Bright Dot	(ignore) (counted) Dot appear bright and unchanged in size when LCD panel is displaying black pattern.	Defect A B Bright Dot 1
	c) Dark Dot	Dot appear dark and unchanged in size when LCD panel is displaying pure color (RED, GREEN or BLUE) pattern.	Dark Dot2NCTotal3NC – Not Count
	d) 2 dot adjacent Type 1 Type 3		DefectAcc. Count2 Bright dot Adjacent02 Dark dot Adjacent1
2	a) Black Spot b) White Spot c) Bright Spot d) Pin Hole e) Foreign Particle	 Black / Dark / Bright Spot is points on display which appear dark/bright and usually result from contamination. These defect do not vary in size intensity (contrast) when contras is varied. 	$\begin{tabular}{ c c c c c c c } \hline Defect Category & A & B \\ \hline D < 0.10 & NC \\ \hline 0.10 \le D \le 0.15 & 2 \\ \hline 0.15 \le D \le 0.20 & 1 \\ \hline D > 0.2 & 0 \end{tabular}$



		b D=(a+b)/2(mm)	
	a) Black Line b) White Line c) Particle between POL and Glass d) Scratch on Glass	L: length (mm)	$\begin{tabular}{ c c c c c } \hline Defect Category & A & B \\ \hline $W < 0.03$ & NC \\ \hline $0.03 \le W \le 0.05$, L & 2 \\ \hline ≤ 2.0 & 0 \\ \hline $W > 0.05$ & 0 \\ \hline \end{tabular}$
	a) POL Bubble b) POL Dented		$\begin{tabular}{ c c c c c } \hline Defect Category & A & B \\ \hline D < 0.20 & NC \\ \hline 0.20 \le D \le 0.30 & 3 \\ \hline 0.30 \le D \le 0.50 & 2 \\ \hline D > 0.5 & 0 \\ \hline \end{tabular}$
3	Mura (50% Grey)		Judged by Limit sample
	Corner Chip		Accept if (only allowed 1):- a) $X \le 1.0$ mm b) $Y \le 1.0$ mm c) $Z \le 1/2$ T
4	Edge Chip	 Touch sensor corner and edge chip that do not cause any damage to tracer and not visible to end-user after housing assembly. Lens edge and corner chip that is not visible to end-user after housing assembly. 	Accept if (only allowed 1):- a) $X \le 1.0$ mm b) $Y \le 1.0$ mm c) $Z \le 1/2T$ T Reject – if the sensor surface edge/corner chip damage circuit and visible from front view
	Glass Crack		Reject – if any crack



5	Printing Ink Light Leakage		Accept if:- Light leakage at marginal area width ≤ 0.15mm
6	Surface Smudginess	 For those that can be cleaned, ≤20% of inspected quantity in one lot under > class 10K area; ≤10% of inspected quantity in one lot ≤ class 10K area. For those that cannot be cleaned it is classified as foreign round shape defect. 	
	FPC Defects on Contact Pad		Accept if dent, pinhole:- a) a ≤ w/3 Reject – if open circuit / cracking / oxidation / contamination
7	FPC Broken		Reject if FPC broken / extruded
	FPC Warped		Accept if FPC warped



9. Precaution

- 1. Handing Precautions
 - a. The display panel is made of glass and polarizer. As glass is fragile. It tends to chip during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock of impact or by dropping it.
 - b. If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance is in contact with your skin or clothes, wash it off using soap and water.
 - c. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degrade the insulation between terminals. Scratch and dents may occur on polarizer too.
 - d. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than a HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.
 - e. If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents.
 - Isopropyl alcohol.
 - Ethyl alcohol.
 - Do not scrub hard to avoid damaging the display surface.
 - f. Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water.
 - Ketone.
 - Aromatic solvents.
 - Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or colour fading. Avoid contact with oil and fats.
 - g. Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.
 - h. Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
 - i. Do not attempt to disassemble or process the LCD module.
 - j. NC terminal should be open. Do not connect anything.
 - k. If the logic circuit power is off, do not apply the input signals.
 - I. Electro-Static Discharge Control. Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Before removing LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
 - Tools required for assembly, such as soldering irons, must be properly grounded. Make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screw driver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.

CRYSTAL CLEAR TECHNOLOGY SDN. BHD

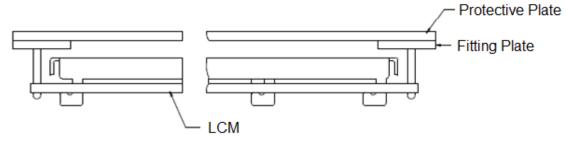
- To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work environment is not too dry. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.
- m. Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.
 - Do not alter, modify or change the shape of the tab on the metal frame.
 - Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
 - Do not damage or modify the pattern writing on the printed circuit board.
 - Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
 - Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
 - Do not drop, bend or twist the LCM.
- 2. Storage Precautions

When storing the LCD modules, the following precaution are necessary.

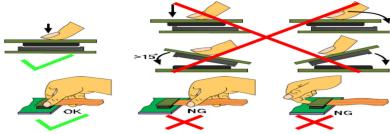
- a. Store the LCD at a temperature from 10°C to 30°C and a relative humidity of 65% RH or less.
- b. Please store display in a dry place and shelter from direct sunlight.
- 3. Others
 - a. Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.
 - b. If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.
 - c. To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc. Exercise care to avoid holding the following sections when handling the modules.
 - Exposed area of the printed circuit board.
 - Terminal electrode sections.
- 4. Using LCD Modules
 - a. Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

b. Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



- c. When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be 0.1mm.
- d. Precaution for assemble the module with BTB connector: Please note the position of the male and female connector position, don't assemble or assemble like the method which the following picture shows.



5. Precaution for soldering the LCM

	Manual soldering	Machine drag soldering	Machine press soldering
No RoHS	290°C ~350°C.	330°C ~350°C.	300°C ~330°C.
Product	Time: 3-5S.	Speed: 4-8 mm/s.	Time: 3-6S.
			Press: 0.8~1.2Mpa
RoHS	340°C ~370°C.	350°C ~370°C.	330°C ~360°C.
Product	Time: 3-5S.	Time: 4-8 mm/s.	Time: 3-6S.
			Press: 0.8~1.2Mpa

- a. If soldering flux is used, be sure to remove any remaining flux after finishing the soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.
- b. When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.
- c. When removing the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.
- 6. Precautions for Operation
 - a. Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.
 - b. It is recommended to drive LCD's within the specified voltage limit since over limit will cause shorter LCD life. An electrochemical reaction due to direct current causes LCD deterioration. Avoid the use of direct current drive.
 - c. Response time will be extremely delayed at lower temperature compared to room operating temperature range and on the other hand, at higher temperature LCD-shows dark colour in them. However those phenomena do not mean malfunction. The LCD will return to normal performance when ambient temperature revert to room condition.
 - d. If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and on.
 - e. A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
 - f. Input logic voltage before apply analogue high voltage such as LCD driving voltage when power on. Remove analogue high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.



- g. Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.
- 7. Safety
 - a. It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.
 - b. If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.
- 8. Limited Warranty

Unless otherwise agreed between Crystal Clear Technology and customer, Crystal Clear Technology will replace or repair any of its LCD and LCM which is found to be defective electrically and visually when inspected in accordance with Crystal Clear Technology acceptance standards, for a period of one year from date of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of Crystal Clear Technology is limited to repair and/or replacement on the terms set forth above. Crystal Clear Technology will not responsible for any subsequent or consequential events.

9. Return LCM under Warranty

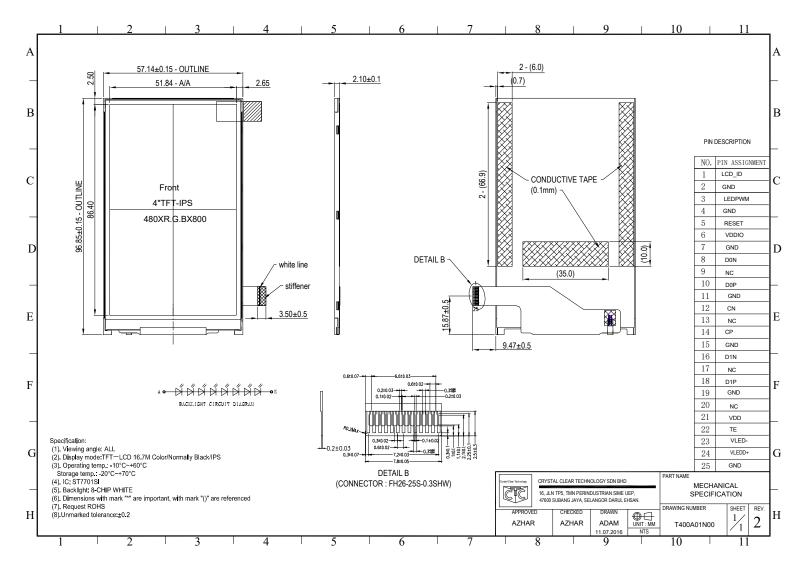
No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are:

- Broken LCD glass.
- PCB eyelet's damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to, or modifying the bezel in any manner.

Module repairs will be invoiced to customer upon mutual agreement. Modules must be returned with sufficient description of failure or defects. Any connectors or cable installed by customer must be removed completely without damaging the PCB eyelet's, conductors and terminals.



10. Mechanical Specification





Spec No. T400A01X00X REV1

